

# ANTREX Electronics

Electronic Components Sourcing Information

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## Product Reference Information

**Part Number:** V3FM10HM3/H  
**Manufacturer:** Vishay General Semiconductor - Diodes Division  
**Package:** DO-219AB  
**Availability:** Please confirm with sales

**Product Page:**

<https://antrexco.com/product/details/vishay-general-semiconductor-diodes-division/v3fm10hm3-h.html>



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## Contact Information

Email: [info@antrexco.com](mailto:info@antrexco.com)

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## Quality & Trust

New & Original Components

Supplier verification and packaging condition review

CoC / RoHS / REACH documents available on request

Secure sourcing support for OEM / EMS projects

**Note:**

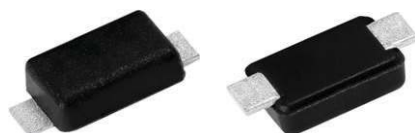
This PDF includes an ANTREX product reference cover page.

The original manufacturer datasheet follows from the next page.

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# Surface-Mount TMBS<sup>®</sup> (Trench MOS Barrier Schottky) Rectifiers

## eSMP<sup>®</sup> Series



Top view

Bottom view

### SMF (DO-219AB)

Cathode  Anode

## LINKS TO ADDITIONAL RESOURCES



3D Models

## PRIMARY CHARACTERISTICS

|                                        |                |
|----------------------------------------|----------------|
| $I_{F(AV)}$                            | 3.0 A          |
| $V_{RRM}$                              | 100 V          |
| $I_{FSM}$                              | 55 A           |
| $V_F$ at $I_F = 3$ A ( $T_A = 125$ °C) | 0.62 V         |
| $T_J$ max.                             | 175 °C         |
| Package                                | SMF (DO-219AB) |
| Circuit configuration                  | Single         |

## FEATURES

- Trench MOS Schottky technology
- Low profile package
- Ideal for automated placement
- Low forward voltage drop, low power losses
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- Wave and reflow solderable
- AEC-Q101 qualified available
  - Automotive ordering code: base P/NHM3
- Compatible to SOD-123W package case outline
- Material categorization: for definitions of compliance please see [www.vishay.com/doc?99912](http://www.vishay.com/doc?99912)


**RoHS**  
COMPLIANT  
HALOGEN  
**FREE**

## TYPICAL APPLICATIONS

For use in high frequency inverters, freewheeling, DC/DC converters, and polarity protection in commercial, industrial, and automotive applications.

## MECHANICAL DATA

### Case: SMF (DO-219AB)

Molding compound meets UL 94 V-0 flammability rating

Base P/N-M3 - halogen-free, RoHS-compliant

Base P/NHM3 - halogen-free, RoHS-compliant, and AEC-Q101 qualified

**Terminals:** matte tin plated leads, solderable per J-STD-002 and JESD 22-B102

M3 and HM3 suffix meet JESD 201 class 2 whisker test

**Polarity:** color band denotes the cathode end

## MAXIMUM RATINGS ( $T_A = 25$ °C unless otherwise noted)

| PARAMETER                                                                          | SYMBOL            | V3FM10      | UNIT |
|------------------------------------------------------------------------------------|-------------------|-------------|------|
| Device marking code                                                                |                   | 3MB         |      |
| Maximum repetitive peak reverse voltage                                            | $V_{RRM}$         | 100         | V    |
| Maximum average forward rectified current (fig.1)                                  | $I_{F(AV)}^{(1)}$ | 2.5         | A    |
|                                                                                    | $I_{F(AV)}^{(2)}$ | 3.0         |      |
| Peak forward surge current 8.3 ms single half sine-wave superimposed on rated load | $I_{FSM}$         | 55          | A    |
| Operating junction temperature range                                               | $T_J^{(3)}$       | -40 to +175 | °C   |
| Storage temperature range                                                          | $T_{STG}$         | -55 to +175 |      |

## Notes

(1) Free air, mounted on FR4 PCB, 2 oz. standard footprint

(2) Mounted on FR4 PCB, 2 oz. 10 mm x 10 mm copper pad areas

(3) The heat generated must be less than the thermal conductivity from junction-to-ambient:  $dP_D/dT_J < 1/R_{\theta JA}$

**ELECTRICAL CHARACTERISTICS** ( $T_A = 25\text{ }^{\circ}\text{C}$  unless otherwise noted)

| PARAMETER                     | TEST CONDITIONS        |                         | SYMBOL                        | TYP. | MAX. | UNIT |
|-------------------------------|------------------------|-------------------------|-------------------------------|------|------|------|
| Instantaneous forward voltage | I <sub>F</sub> = 1.5 A | T <sub>A</sub> = 25 °C  | V <sub>F</sub> <sup>(1)</sup> | 0.59 | -    | V    |
|                               | I <sub>F</sub> = 3.0 A |                         |                               | 0.74 | 0.83 |      |
|                               | I <sub>F</sub> = 1.5 A | T <sub>A</sub> = 125 °C |                               | 0.52 | -    |      |
|                               | I <sub>F</sub> = 3.0 A |                         |                               | 0.62 | 0.70 |      |
| Reverse current               | V <sub>R</sub> = 70 V  | T <sub>A</sub> = 25 °C  | I <sub>R</sub> <sup>(2)</sup> | 0.7  | -    | μA   |
|                               |                        | T <sub>A</sub> = 125 °C |                               | 500  | -    |      |
|                               | V <sub>R</sub> = 100 V | T <sub>A</sub> = 25 °C  |                               | -    | 85   |      |
|                               |                        | T <sub>A</sub> = 125 °C |                               | 900  | 3000 |      |
| Typical junction capacitance  | 4.0 V, 1 MHz           |                         | C <sub>J</sub>                | 240  | -    | pF   |

**Notes**(1) Pulse test: 300  $\mu\text{s}$  pulse width, 1 % duty cycle(2) Pulse test: Pulse width  $\leq 5\text{ ms}$ **THERMAL CHARACTERISTICS** ( $T_A = 25\text{ }^{\circ}\text{C}$  unless otherwise noted)

| PARAMETER                  | SYMBOL                   | V3FM10 | UNIT                 |
|----------------------------|--------------------------|--------|----------------------|
| Typical thermal resistance | $R_{\theta JA}^{(1)(2)}$ | 125    | $^{\circ}\text{C/W}$ |
|                            | $R_{\theta JM}^{(3)}$    | 22     |                      |

**Notes**(1) The heat generated must be less than the thermal conductivity from junction-to-ambient:  $dP_D/dT_J < 1/R_{\theta JA}$ (2) Device mounted on FR4 PCB, 2 oz. standard footprint, thermal resistance  $R_{\theta JA}$  – junction-to-ambient(3) Device mounted on 10 mm x 10 mm pad size area footprint; thermal resistance  $R_{\theta JM}$  – junction-to-mount**ORDERING INFORMATION** (Example)

| PREFERRED P/N              | UNIT WEIGHT (g) | PREFERRED PACKAGE CODE | BASE QUANTITY | DELIVERY MODE                      |
|----------------------------|-----------------|------------------------|---------------|------------------------------------|
| V3FM10-M3/H                | 0.015           | H                      | 3000          | 7" diameter plastic tape and reel  |
| V3FM10-M3/I                | 0.015           | I                      | 10 000        | 13" diameter plastic tape and reel |
| V3FM10HM3/H <sup>(1)</sup> | 0.015           | H                      | 3000          | 7" diameter plastic tape and reel  |
| V3FM10HM3/I <sup>(1)</sup> | 0.015           | I                      | 10 000        | 13" diameter plastic tape and reel |

**Note**

(1) AEC-Q101 qualified

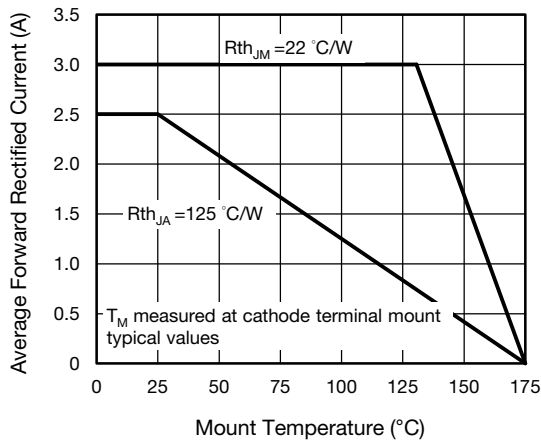
**RATINGS AND CHARACTERISTICS CURVES** ( $T_A = 25\text{ }^{\circ}\text{C}$  unless otherwise noted)


Fig. 1 - Maximum Forward Current Derating Curve

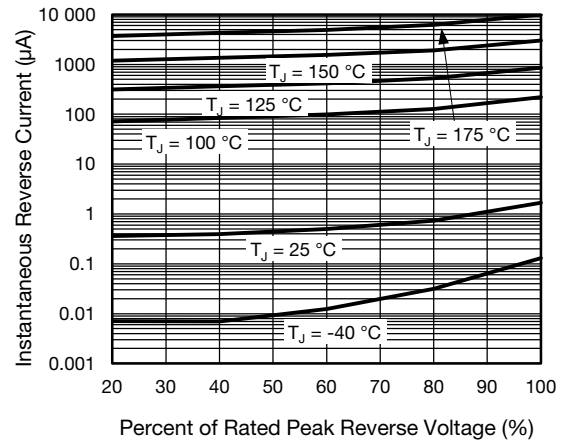


Fig. 4 - Typical Reverse Leakage Characteristics

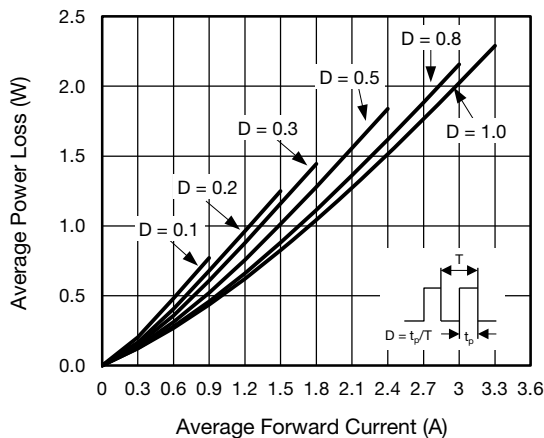


Fig. 2 - Average Power Loss Characteristics

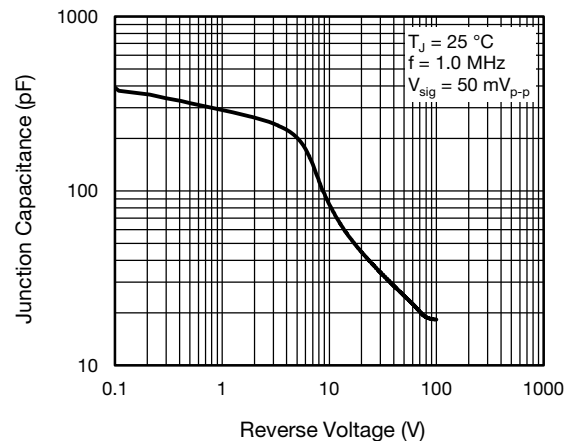


Fig. 5 - Typical Junction Capacitance

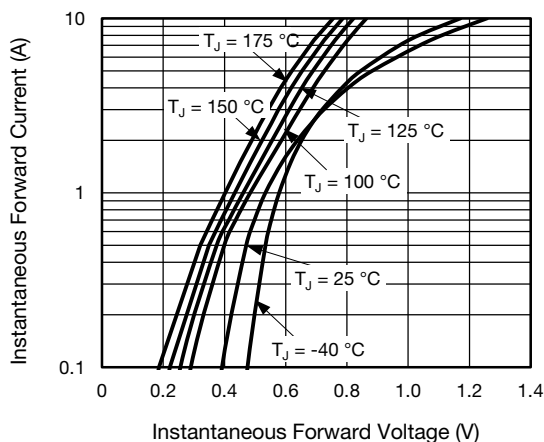


Fig. 3 - Typical Instantaneous Forward Characteristics

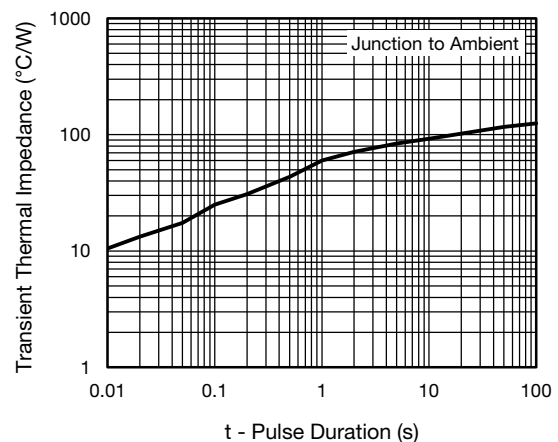
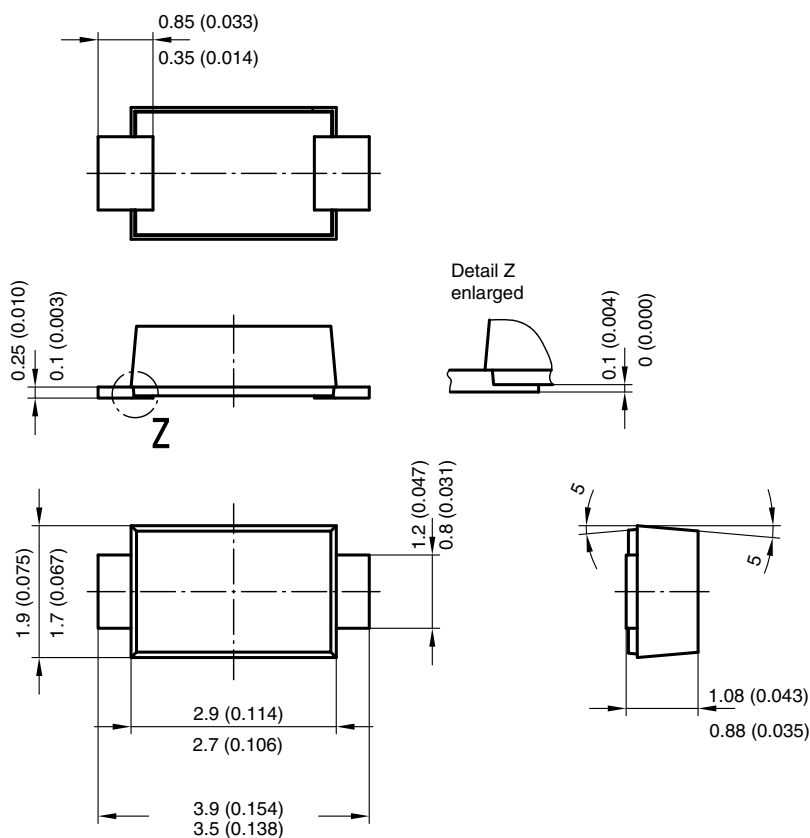
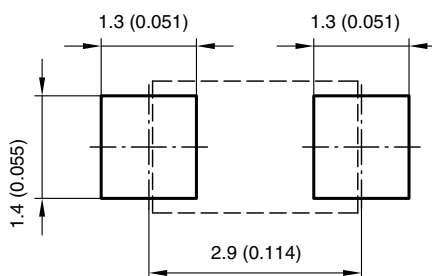


Fig. 6 - Typical Transient Thermal Impedance

**PACKAGE OUTLINE DIMENSIONS** in millimeters (inches)


Foot print recommendation:



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